

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>5</b>	<b>device and mounting near substrate and pressing and mounting adj pads and project\$3 near electrodes</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 11:03</b>
<b>2</b>	<b>20</b>	<b>Murakami near Tomoo .inv.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 11:03</b>
<b>-</b>	<b>0</b>	<b>device and substrate and mounting and pressing and deforming and sealling and 29/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 10:57</b>
<b>-</b>	<b>644</b>	<b>device and substrate and mounting and pressing and 29/\$.ccls.</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 10:57</b>
<b>-</b>	<b>4</b>	<b>device and substrate and mounting and pressing and 29/\$.ccls. and mounting adj pads and project\$3 near electrodes</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 10:59</b>
<b>-</b>	<b>4</b>	<b>device and substrate and mounting and pressing and (74/260, 174/256 , 174/261 , 257/E21.503 , 257/E21.511 , 257/E23.021 , 29/831 , 29/832 , 29/840).ccls. and mounting adj pads and project\$3 near electrodes</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 11:01</b>
<b>-</b>	<b>4</b>	<b>device and substrate and mounting and pressing and (29/830; 29/832 ; 29/836 ; 29/840 ; 29/739 ; 29/841 ; 29/838 ; 29/839 ; 29/837 ; 228/180.22 ; 257/772 ; 257/773 ; 257/775 ; 257/737 ; 257/778 ; 361/768 ; 361/773 ; 361/774 ; 174/260 ).ccls. and mounting adj pads and project\$3 near electrodes</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2004/06/11 11:01</b>

	<b>Title</b>	<b>Current OR</b>
<b>1</b>	<b>Image recording material and lithographic printing plate precursor</b>	<b>430/270.1</b>
<b>2</b>	<b>Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance</b>	<b>438/108</b>
<b>3</b>	<b>Method of mounting a semiconductor device to a substrate and a mounted structure</b>	<b>29/840</b>
<b>4</b>	<b>METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE</b>	<b>174/260</b>
<b>5</b>	<b>Mounting method and apparatus of bare chips</b>	<b>438/113</b>
<b>6</b>	<b>Semiconductor device and semiconductor device mounting method thereof</b>	<b>257/684</b>
<b>7</b>	<b>Method for mounting flip chip on circuit board through reliable electrical connections at low contact resistance</b>	<b>438/108</b>

	<b>Current XRef</b>
<b>1</b>	<b>430/302</b>
<b>2</b>	<b>257/E21.503; 257/E21.508</b>
<b>3</b>	<b>174/250; 174/260; 174/263; 257/E21.503; 257/E21.511; 257/E23.021; 29/854</b>
<b>4</b>	<b>174/256; 174/261; 257/E21.503; 257/E21.511; 257/E23.021; 29/831; 29/832; 29/840</b>
<b>5</b>	<b>257/E21.503; 257/E21.508; 257/E21.514</b>
<b>6</b>	<b>257/737; 257/E21.503; 438/612; 438/615</b>
<b>7</b>	<b>228/180.22; 257/778; 257/E21.503; 257/E21.508; 438/127; 438/666</b>

	<b>Title</b>	<b>Current OR</b>
<b>8</b>	<b>Method of mounting a semiconductor device to a substrate</b>	<b>29/840</b>
<b>9</b>	<b>Flip chip mounting method and apparatus therefor</b>	<b>29/840</b>
<b>10</b>	<b>Semiconductor element mounting method</b>	<b>438/108</b>
<b>11</b>	<b>Method for producing a semiconductor device</b>	<b>438/108</b>

	<b>Title</b>	<b>Current OR</b>
<b>12</b>	<b>Method for manufacturing wiring pattern board</b>	<b>427/96</b>
<b>13</b>	<b>Method of mounting a semiconductor device to a substrate and a mounted structure</b>	<b>257/775</b>
<b>14</b>	<b>Method for manufacturing a printed circuit board having electrodes on end surface of substrate</b>	<b>29/852</b>
<b>15</b>	<b>Method for manufacturing printed circuit board with through-hole</b>	<b>29/852</b>
<b>16</b>	<b>Method of and apparatus for plating printed circuit board</b>	<b>427/98</b>

	<b>Title</b>	<b>Current OR</b>
<b>17</b>	<b>Fabrication method of printed wiring board</b>	<b>427/510</b>
<b>18</b>	<b>Silver halide photographic material containing a silica containing overlayer and specific hydrazine derivatives</b>	<b>430/264</b>
<b>19</b>	<b>CONNECTION STRUCTURE BETWEEN PRINTED BOARDS</b>	
<b>20</b>	<b>Image recording material and lithographic printing plate precursor</b>	

	<b>Title</b>	<b>Current OR</b>
<b>1</b>	<b>Method of mounting a semiconductor device to a substrate and a mounted structure</b>	<b>29/840</b>
<b>2</b>	<b>METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE</b>	<b>174/260</b>
<b>3</b>	<b>Method of mounting a semiconductor device to a substrate</b>	<b>29/840</b>

	<b>Current XRef</b>
<b>1</b>	<b>174/250;</b> <b>174/260;</b> <b>174/263;</b> <b>257/E21.503;</b> <b>257/E21.511;</b> <b>257/E23.021;</b> <b>29/854</b>
<b>2</b>	<b>174/256;</b> <b>174/261;</b> <b>257/E21.503;</b> <b>257/E21.511;</b> <b>257/E23.021;</b> <b>29/831;</b> <b>29/832;</b> <b>29/840</b>
<b>3</b>	<b>174/260;</b> <b>257/738;</b> <b>257/772;</b> <b>257/773;</b> <b>257/775;</b> <b>257/778;</b> <b>257/E21.503;</b> <b>257/E21.511;</b> <b>257/E23.021;</b> <b>29/739;</b> <b>29/832;</b> <b>29/837;</b> <b>29/841;</b> <b>361/768;</b> <b>361/773;</b> <b>361/774</b>